



GE Energy

Functional Testing Specification

Parts & Repair Services
Louisville, KY

LOU-GED-DS200DTBB

Test Procedure for a terminal board.

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| REV. | DESCRIPTION | SIGNATURE | REV. DATE |
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| DATE 12/17/2013 | DATE | DATE | DATE 12/17/2013 |

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| LOU-GED-DS200DTBB REV. A | g GE Energy <i>Parts & Repair Services</i> <i>Louisville, KY</i> | Page 2 of 4 |
|-----------------------------|--|-------------|

1. SCOPE

1.1 This is a functional testing procedure for a terminal board.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check board's electronic folder for more information

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires - broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors - broken or cracked

4.2.1.3 Components - visually damaged

4.2.1.4 Capacitors - bloated or leaking

4.2.1.5 Solder joints - damaged or cold

4.2.1.6 Circuit board - burned or de-laminated

4.2.1.7 Printed wire runs / Traces - burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

| Qty | Reference # | Description |
|-----|-------------|------------------------------|
| 1 | | Fluke 87 DMM (or Equivalent) |
| | | |

6. Testing Procedures

6.1 Make sure all jumpers are in place.

6.2 Check the following points:

| From Terminal Connector | To JRT, JRS, JRR | Value | From | To | Value |
|-------------------------------|---------------------|------------------------|------|-----|-------------|
| 1 | 1 | 750k Ω (+/- 5%) | 2 | JY1 | <1 Ω |
| 3 | 2 | 750k Ω (+/- 5%) | 4 | JY1 | <1 Ω |
| 5 | 3 | 750k Ω (+/- 5%) | 6 | JY1 | <1 Ω |
| 7 | 4 | 750k Ω (+/- 5%) | 8 | JY1 | <1 Ω |
| 9 | 5 | 750k Ω (+/- 5%) | 10 | JY1 | <1 Ω |
| 11 | 6 | 750k Ω (+/- 5%) | 12 | JY1 | <1 Ω |
| 13 | 7 | 750k Ω (+/- 5%) | 14 | JY1 | <1 Ω |
| 15 | 8 | 750k Ω (+/- 5%) | 16 | JY1 | <1 Ω |
| 17 | 9 | 750k Ω (+/- 5%) | 18 | JY1 | <1 Ω |
| 19 | 10 | 750k Ω (+/- 5%) | 20 | JY1 | <1 Ω |
| 21 | 11 | 750k Ω (+/- 5%) | 22 | JY1 | <1 Ω |
| 23 | 12 | 750k Ω (+/- 5%) | 24 | JY1 | <1 Ω |
| 25 | 13 | 750k Ω (+/- 5%) | 26 | JY1 | <1 Ω |
| 27 | 14 | 750k Ω (+/- 5%) | 28 | JY1 | <1 Ω |
| 29 | 15 | 750k Ω (+/- 5%) | 30 | JY1 | <1 Ω |
| 31 | 16 | 750k Ω (+/- 5%) | 32 | JY1 | <1 Ω |
| 33 | 17 | 750k Ω (+/- 5%) | 34 | JY1 | <1 Ω |
| 35 | 18 | 750k Ω (+/- 5%) | 36 | JY1 | <1 Ω |
| 37 | 19 | 750k Ω (+/- 5%) | 38 | JY1 | <1 Ω |
| 39 | 20 | 750k Ω (+/- 5%) | 40 | JY1 | <1 Ω |
| 41 | 21 | 750k Ω (+/- 5%) | 42 | JY1 | <1 Ω |
| 43 | 22 | 750k Ω (+/- 5%) | 46 | JY1 | <1 Ω |
| 45 | 23 | 750k Ω (+/- 5%) | 48 | JY1 | <1 Ω |
| 47 | 24 | 750k Ω (+/- 5%) | 50 | JY1 | <1 Ω |
| 49 | 25 | 750k Ω (+/- 5%) | 52 | JY1 | <1 Ω |
| 51 | 26 | 750k Ω (+/- 5%) | 54 | JY1 | <1 Ω |
| 53 | 27 | 750k Ω (+/- 5%) | 56 | JY1 | <1 Ω |
| 55 | 28 | 750k Ω (+/- 5%) | 58 | JY1 | <1 Ω |
| 57 | 29 | 750k Ω (+/- 5%) | 60 | JY1 | <1 Ω |
| 59 | 30 | 750k Ω (+/- 5%) | 62 | JY1 | <1 Ω |
| 61 | 31 | 750k Ω (+/- 5%) | 64 | JY1 | <1 Ω |
| | | | 66 | JY1 | <1 Ω |

| From | To | Value | From | To | Value |
|--------------------|---------------|------------------------|------|-----|-------------|
| Terminal Connector | JRT, JRS, JRR | | | | |
| 63 | 32 | 750k Ω (+/- 5%) | 68 | JY1 | <1 Ω |
| 65 | 33 | 750k Ω (+/- 5%) | 70 | JY1 | <1 Ω |
| 67 | 34 | 750k Ω (+/- 5%) | 72 | JY1 | <1 Ω |
| 69 | 35 | 750k Ω (+/- 5%) | 74 | JY1 | <1 Ω |
| 71 | 36 | 750k Ω (+/- 5%) | 76 | JY1 | <1 Ω |
| 73 | 37 | 750k Ω (+/- 5%) | 78 | JY1 | <1 Ω |
| 75 | 38 | 750k Ω (+/- 5%) | 80 | JY1 | <1 Ω |
| 77 | 39 | 750k Ω (+/- 5%) | 82 | JY1 | <1 Ω |
| 79 | 40 | 750k Ω (+/- 5%) | 84 | JY1 | <1 Ω |
| 81 | 41 | 750k Ω (+/- 5%) | 86 | JY1 | <1 Ω |
| 83 | 42 | 750k Ω (+/- 5%) | 88 | JY1 | <1 Ω |
| 85 | 43 | 750k Ω (+/- 5%) | 90 | JY1 | <1 Ω |
| 87 | 44 | 750k Ω (+/- 5%) | 92 | JY1 | <1 Ω |
| 89 | 45 | 750k Ω (+/- 5%) | 94 | JY1 | <1 Ω |
| 91 | 46 | 750k Ω (+/- 5%) | 96 | JY1 | <1 Ω |
| 93 | 47 | 750k Ω (+/- 5%) | 98 | JY1 | <1 Ω |
| 95 | 48 | 750k Ω (+/- 5%) | 100 | JY1 | <1 Ω |
| 97 | 49 | 750k Ω (+/- 5%) | | | |
| 99 | 50 | 750k Ω (+/- 5%) | | | |

6.3 Check all resistor networks Pins 1 and 3 to JY2 for 150K (+/- 5%).

6.4 For all normal repairs; card does not have any active components so unit does not require any burn-in.

6.4*TEST COMPLETE *****

7. Notes

7.1 None at this time.

8. Attachments

8.1 None at this time.